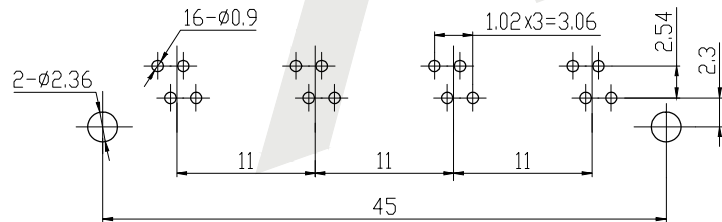
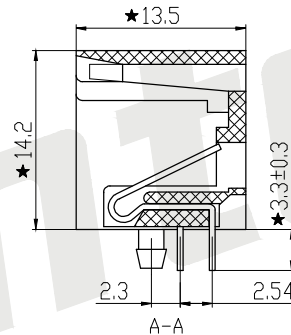
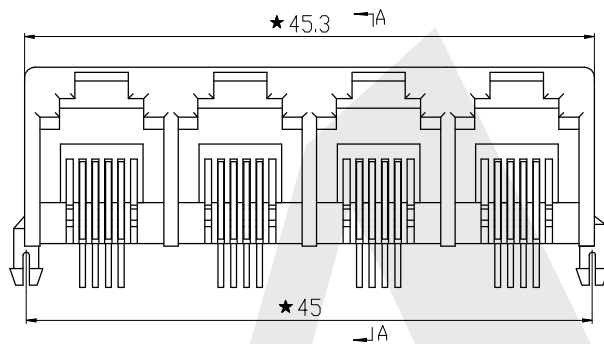
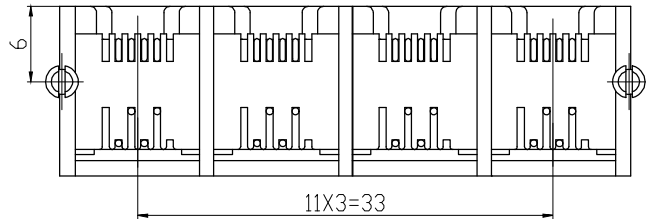


HSF

RoHS



PC Board layout

NOTES:

MATERIAL:

- HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
- CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
- PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
- SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

- VOLTAGE RATING: 125VAC RMS
- CURRENT RATING: 1.5AMP
- CONTACT RESISTANCE: 30MILLIOHMS MAX
- INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
- DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

- DURRABILITY: 750 CYCLES MIN
- PCB RETENTTON PRB-SOLDER: 1 LB MIN

REIVRONMENTAL

- STORAGE: -40°C TO 85°C
- OPERATION: 0°C TO 70°C

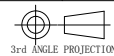
Order code:

ATRJ5523 - 6P - 4C - X - X - C

- | | |
|------------------------------------|-------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: G0ld flash | D: Shield W/O Eml |
| G1: 3U" Gold | ⑥ Ports |
| G2: 5U" Gold | A: 1X1P |
| G3: 10U" Gold | B: 1X2P |
| G4: 15U" Gold | C: 1X4P |
| G5: 30U" Gold | D: 1X5P |
| SN: Tin | E: 1X6P |
| | F: 1X8P |

Unless Otherwise specified tolerance
 X. ± 0.35 X.XX: ± 0.20
 X.X: ± 0.25 X.XXX: ± 0.15

SCALE: As Shown UNIT: mm
 DRAW Wu Feng Rong DATE 11/09/2019
 CHECK BobYang DATE 11/09/2019



Antenk ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE:
 RJ11 JACK RIGHT ANGLE FULL PLASTIC 1X4PORT

DRAWING NO: ATRJ5523-6P4C-XX-1x4P

PRODUCT NO: ATRJ5523-6P4C-XX-1x4P

REV	DESCRIPTION	DATE